

BTB12-600BW3G, BTB12-800BW3G





Description

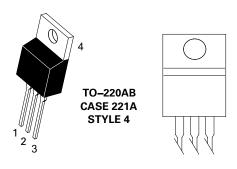
Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

Features

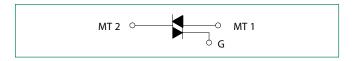
- Blocking Voltage to 800 V
- On-State Current Rating of 12 Amperes RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt

 2000 V/µs minimum at
 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dl/ dt – 4. A/ms minimum at 125°C
- These are Pb–Free Devices

Pin Out



Functional Diagram



Additional Information







Samples



Maximum Ratings $(T_1 = 25^{\circ}C \text{ unless otherwise noted})$

Rating		Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J = -40^{\circ}$ to 150°C)	BTB12-600BW3G BTB12-800BW3G	V _{DRM} , V _{RRM}	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T _C = 80°C)		I _{T (RMS)}	12	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T_c = 25°C)		I _{TSM}	125	А
Circuit Fusing Consideration (t = 8.3 ms)		l²t	78	A²sec
Non-Repetitive Surge Peak Off-State Voltage ($T_J = 25^{\circ}\text{C}$, t = 10 ms)		V _{DSM} /V _{RSM}	V _{DSM} /V _{RSM} +100	V
Peak Gate Current (T _J = 125°C, t = 20ms)		I _{GM}	4.0	W
Peak Gate Power (Pulse Width \leq 1.0 μ s, T_{C} = 80°C)		P _{GM}	20	W
Average Gate Power (T _J = 125°C)		P _{G(AV)}	1.0	W
Operating Junction Temperature Range		T _J	-40 to +125	°C
Storage Temperature Range		T _{stg}	-40 to +125	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance	Junction-to-Case (AC) Junction-to-Ambient	R _{euc} R _{eua}	2.5 60	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		T _L	260	°C

Electrical Characteristics - **OFF** $(T_j = 25^{\circ}\text{C unless otherwise noted}; Electricals apply in both directions)$

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T ₁ = 25°C	I _{DRM} ,	-	-	0.005	m A
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	T _J = 125°C	I _{RRM}	-	-	1.0	mA

Electrical Characteristics - ON (T_J = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Forward On-State Voltage (Note 2) ($I_{TM} = \pm 17 \text{ A Peak}$)	•	V _{TM}	-	-	1.55	V
	MT2(+), G(+)		2.5	-	50	
Gate Trigger Current (Continuous dc) ($V_D = 12 \text{ V}, R_L = 30 \Omega$)	MT2(+), G(-)	l _{GT}	2.5	_	50	mA
	MT2(-), G(-)		2.5	-	50	
Holding Current ($V_D = 12 \text{ V}$, Gate Open, Initiating Current = $\pm 100 \text{ mA}$)		I _H	-	_	50	mA
	MT2(+), G(+)		-	_	70	
Latching Current ($V_D = 24 \text{ V}, I_G = 60 \text{ mA}$)	MT2(+), G(-)	IL	-	-	90	mA
	MT2(-), G(-)		-	_	70	
	MT2(+), G(+)		0.5	-	1.7	
Gate Trigger Voltage ($V_D = 12 \text{ V}, R_L = 30 \Omega$)	MT2(+), G(-)	V _{GT}	0.5	-	1.1	V
	MT2(-), G(-)		0.5	-	1.1	
	MT2(+), G(+)		0.2	-	-	
Gate Non-Trigger Voltage ($T_J = 125$ °C)	MT2(+), G(-)	V _{GD}	0.2	-	-	V
	MT2(-), G(-)		0.2	-	_	

V_{DBM} and V_{BBM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



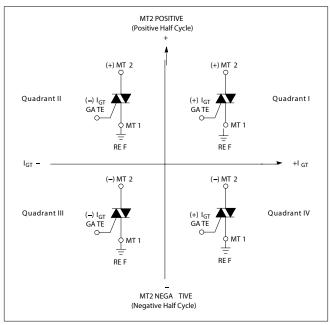
Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, $T_J = 125$ °C, No Snubber)	(dl/dt)c	4.0	-	_	A/ms
Critical Rate of Rise of On–State Current ($T_J = 125$ °C, $f = 120$ Hz, $I_G = 2 \times I_{GT}$, $tr \le 100$ ns)	dl/dt	-	-	50	A/µs
Critical Rate of Rise of Off-State Voltage ($V_D = 0.66 \times V_{DRM'}$ Exponential Waveform, Gate Open, $T_J = 125^{\circ}$ C)	dV/dt	2000	-	_	V/µs

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I _{DRM}	Peak Forward Blocking Current
V _{RRM}	Peak Repetitive Reverse Off State Voltage
I _{RRM}	Peak Reverse Blocking Current
V _{TM}	Maximum On State Voltage
I _H	Holding Current

Quadrant Definitions for a Triac



All polarities are referenced to MT1. With in–phase signals (using standard AC lines) quadrants I and III are used

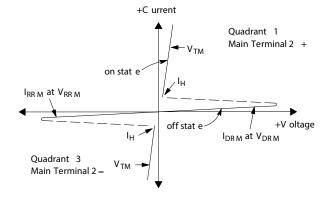


Figure 2. On-State Power Dissipation



Figure 1. RMS Current Derating

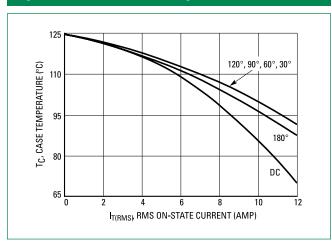


Figure 4. Thermal Response

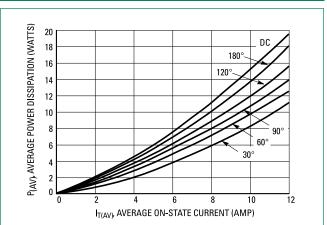
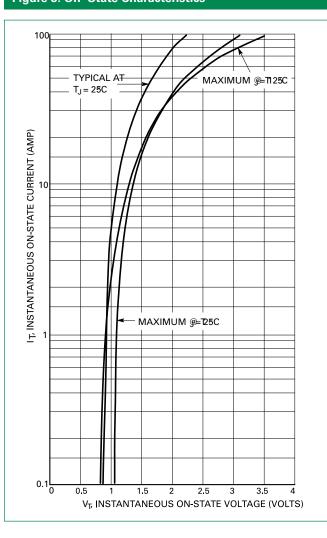


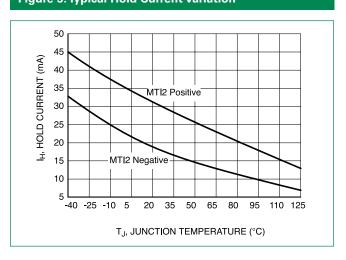
Figure 3. On-State Characteristics



r(t), TRANSIENT THERMAL RESISTANCE (NORMALIZED)

t, TIME (ms)

Figure 5. Typical Hold Current Variation



1000

1 · 104





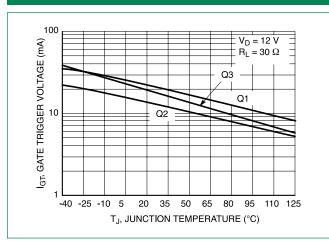


Figure 7. Typical Gate Trigger Voltage Variation

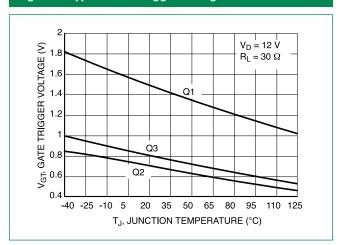


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential Waveform)

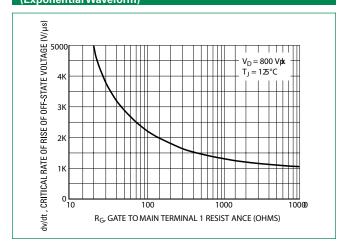
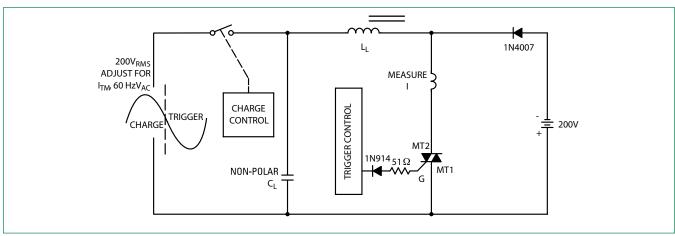


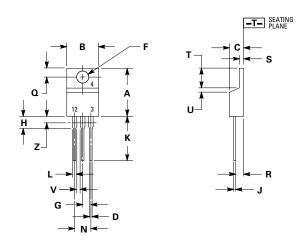
Figure 9. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)



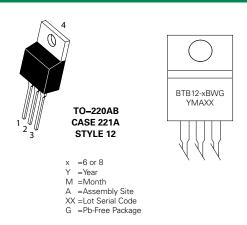
Note: Component values are for verification of rated (di/dt)c. See AN1048 for additional information



Dimensions



Part Marking System



Dim	Inches		Millin	neters
Dim	Min	Max	Min	Max
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
Н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
s	0.045	0.060	1.14	1.52
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	_
Z	_	0.080	_	2.04

Pin Assignment			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	No Connection		

Ordoring	Information
Orograma	Information

Device	Package	Shipping
BTB12-600BW3G	TO-220AB (Pb-Free)	500 Units / Rail
BTB12-800BW3G	TO-220AB (Pb-Free)	500 Units / Rail

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

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